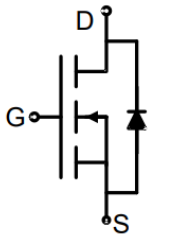
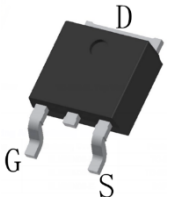
1. Description

The BLM06N03 uses advanced trench technology to provide excellent RDS(ON), low gate charge. It can be used in a wide variety of applications.

KEY CHARACTERISTICS

Parameter	Value	Unit
V_{DS}	30	V
I_D	70	A
$R_{DS(ON)}$@10V.Typ	6.0	mΩ
$R_{DS(ON)}$@4.5V.Typ	9.5	mΩ





TO-252

FEATURES

- Advanced Trench Technology
- Excellent RDS(ON) and Low Gate Charge
- LeadFree

APPLICATIONS

- LoadSwitch
- PWMApplication
- PowerManagement

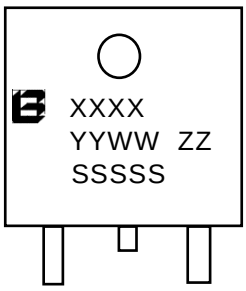
100% UIS TESTED!
100% ΔVds TESTED!

ORDERING INFORMATION

Device Marking	Ordering Codes	Package	Product Code	Packing
M06N03	BLM06N03-D	TO-252	BLM06N03	Reel

BLM06N03-D
(2) Package type
(1) Chip name

(1)BLM06N03:30V 6mΩ



XXXX：Product Code
YYWW：Year&Week
ZZ：Assembly Code
SSSSS：Lot Code

2. ABSOLUTE RATINGS

at T_C = 25°C, unless otherwise specified

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	30	V
I_D	Continuous Drain Current	70	A
$I_{DM(Note1)}$	Pulsed Drain Current	280	A
P_D	Power Dissipation	50	W
V_{GS}	Gate-to-Source Voltage	±20	V
E_{AS}	Single Pulse Avalanche Energy(Note2)	56	mJ
T_J，T_{stg}	Operating Junction and Storage Temperature Range	–55 to 150	℃

3. Thermal characteristics

Thermal characteristics

Symbol	Parameter	RATINGS	Units
$R_{\theta JC}$	Junction-to- Case	2.5	℃/W

4. Electrical Characteristics

at T_C = 25°C, unless otherwise specified

OFF Characteristics						
Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	V_{GS}=0V, I_D=250μA	30	--	--	V
I_{DSS}	Drain to Source Leakage Current	V_{DS} =30V, V_{GS}= 0V	--	--	1	μA
I_{GSS}	Gate to Source Forward Leakage	V_{GS} =±20V	--	--	100	nA

ON Characteristics						
Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$ (Note3)	Drain-to-Source On-Resistance	VGS=10V, ID=30A,	--	4.6	6.0	mΩ
		VGS=4.5V, ID=20A,	--	7.3	9.5	
$V_{GS(TH)}$	Gate Threshold Voltage	VDS = VGS, ID = 250μA(Note2)	1.0	1.6	2.5	V

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
C_{iss}	Input Capacitance	VGS = 0V VDS = 25V f = 1.0MHz	--	1788	--	pF
C_{oss}	Output Capacitance		--	800	--	
C_{rss}	Reverse Transfer Capacitance		--	639	--	

Switching Characteristics

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	VDD = 60V ID=30A RL =1.2Ω RGEN =3Ω VGS = 10V	--	11	--	ns
tr	Rise Time		--	5	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	25	--	
t_f	Fall Time		--	8	--	
Q_g	Total Gate Charge	ID =30A VDD =15V VGS = 10V	--	28.3	--	nC
Q_{gs}	Gate to Source Charge		--	4.12	--	
Q_{gd}	Gate to Drain (“Miller”)Charge		--	6.42	--	

Source-Drain Diode Characteristics

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
I_S	Continuous Source Current (Body Diode)	TC=25 °C	--	--	70	A
V_{SD}	Diode Forward Voltage	IS=20A, VGS=0V(Note2)	--	--	1.2	V

Note1: Pulse width limited by maximum junction temperature
Note2: Eas condition：Tj=25℃， VG=10V,L=0.5mH,Ias=15A
Note3: Pulse width tp≤300μs, δ≤2%

5. Characteristics Curves

Figure 1 Output Characteristics

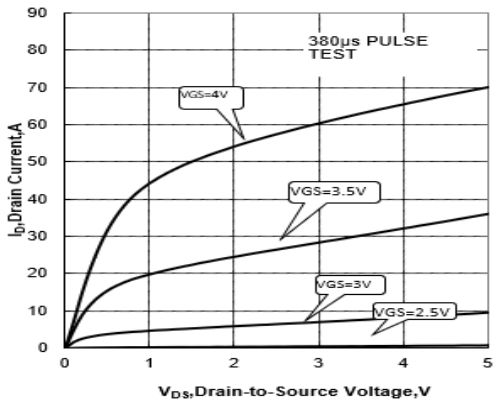


Figure 2 Transfer Characteristics

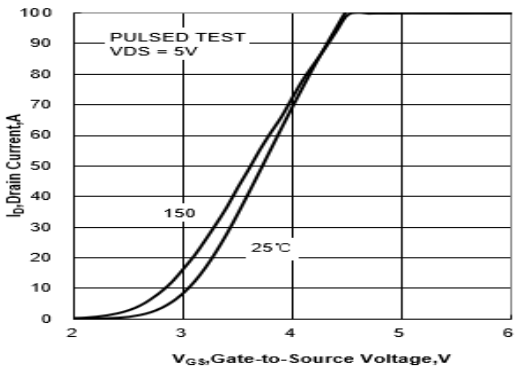


Figure 3 On-Resistance vs. I_D

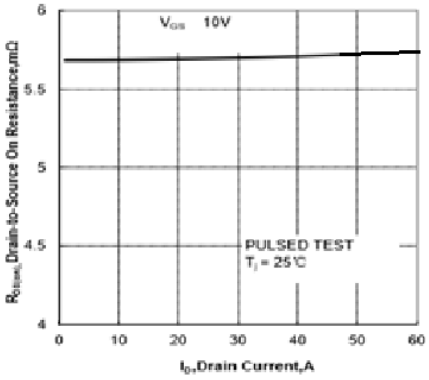


Figure 4 On-Resistance vs. Junction Temperature

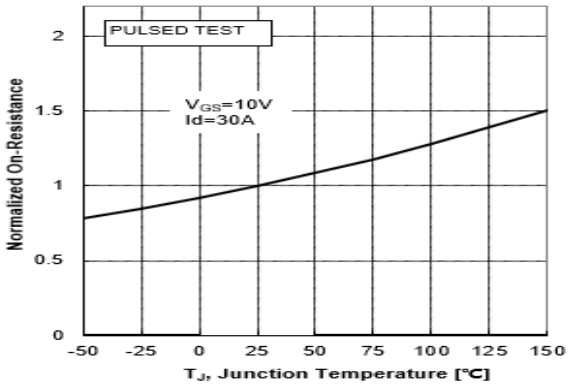


Figure 5 BV vs Junction Temperature

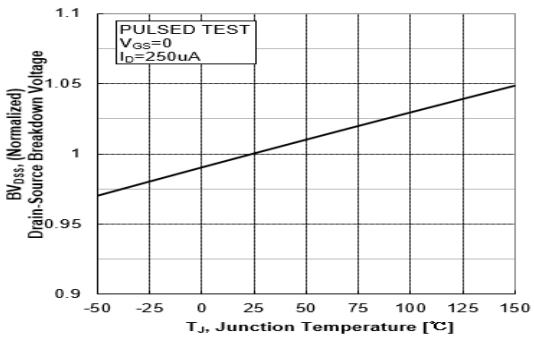


Figure 6 Vth vs Junction Temperature

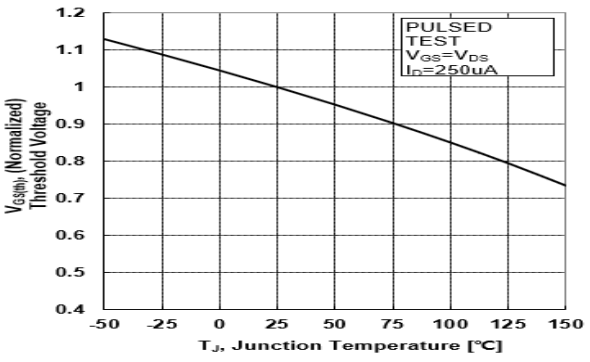


Figure 7 Gate-Charge Characteristics

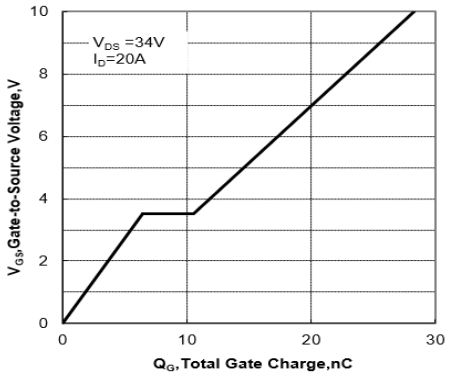


Figure 8 Capacitance Characteristics

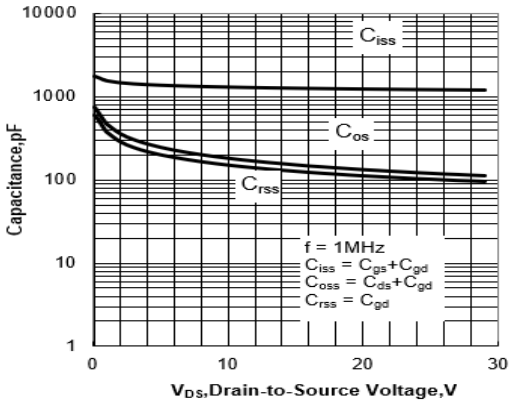


Figure 9 Body Diode Forward Voltage

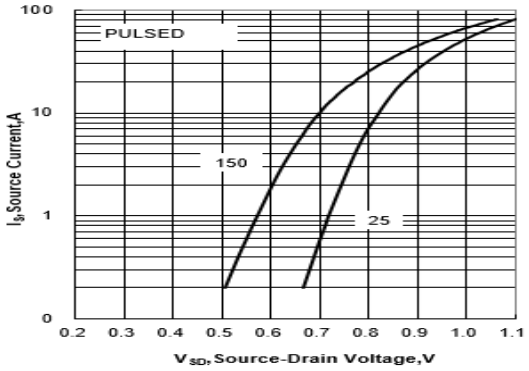


Figure 10 Maximum Safe Operating Area

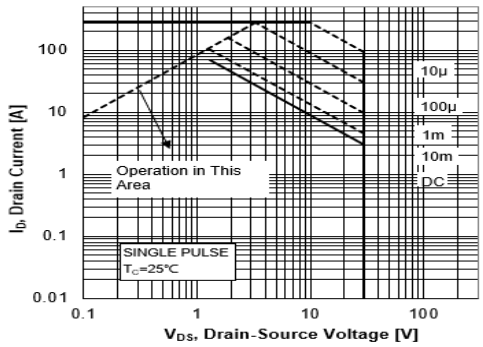
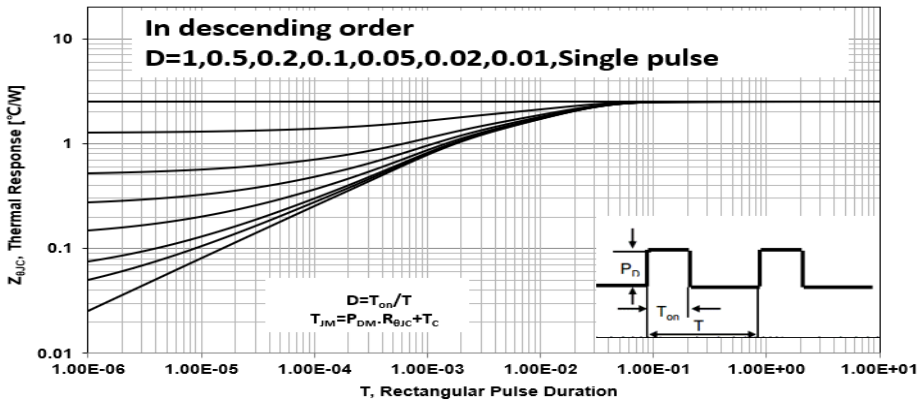
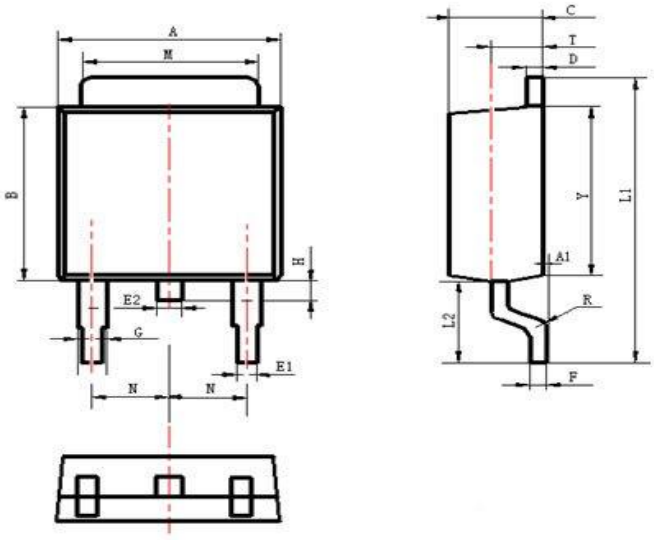


Figure 11 Transient Thermal Impedance



Package Description



Items	Values(mm)	
	MIN	MAX
A	6.30	6.90
A1	0	0.13
B	5.70	6.30
C	2.10	2.50
D	0.30	0.60
E1	0.60	0.90
E2	0.70	1.00
F	0.30	0.60
G	0.70	1.20
L1	9.60	10.50
L2	2.70	3.10
H	0.60	1.00
M	5.10	5.50
N	2.09	2.49
R	0 .3	
T	1.40	1.60
Y	5.10	6.30

TO-252 Package

NOTE:

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. Please do not exceed the absolute maximum ratings of the device when circuit designing.
2. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
3. MOSFETs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. Shanghai Belling reserves the right to make changes in this specification sheet and is subject to change without prior notice.

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